

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) An internal electrode paste, comprising electrode material powder, a binder resin containing a polyvinyl butyral resin and/or a polyvinyl acetal resin as the main component, and a solvent.
2. (Original) The internal electrode paste as set forth in claim 1, furthermore comprising a plasticizer, wherein said plasticizer is contained by 25 parts by weight or more and 150 parts by weight or less with respect to 100 parts by weight of said binder resin.
3. (Currently Amended) The internal electrode paste as set forth in claim 1 ~~or 2~~, wherein said binder resin is contained by 2.5 to 5.5 parts by weight with respect to 100 parts by weight of said electrode material powder.
4. (Currently Amended) The internal electrode paste as set forth in claim 1 ~~any one of claims 1 to 3~~, furthermore comprising ceramic powder.
5. (Original) The internal electrode paste as set forth in claim 4, wherein said binder resin is contained by 2.5 to 5.5 parts by weight with respect to a total of 100 parts by weight of said electrode material powder and ceramic powder.
6. (Currently Amended) The internal electrode paste as set forth in claim 1 ~~any one of claims 1 to 5~~, wherein said electrode material powder is contained by 50 wt% or less with respect to the entire internal electrode paste.
7. (Currently Amended) The internal electrode paste as set forth in claim 1 ~~any one of claims 1 to 6~~, wherein a polymerization degree of said polyvinyl butyral resin and/or a polyvinyl acetal resin is 1400 or more and 3600 or less.
8. (Currently Amended) The internal electrode paste as set forth in claim 1 ~~any one of claims 1 to 7~~, wherein an acetalization degree of said polyvinyl acetal resin is 74 mol% or less.

9. (Currently Amended) A production method of an electronic device, comprising the steps of:
preparing the internal electrode paste as set forth in claim 1 ~~any one of claims 1 to 8~~;
forming a green sheet;
forming an internal electrode layer by using said internal electrode layer paste;
stacking said green sheets via internal electrode layers to obtain a green chip; and
firing said green chip.

10. (Currently Amended) A production method of an electronic device, comprising the steps of:
forming an electrode layer on a surface of a first supporting sheet by using the internal electrode paste as set forth in claim 1 ~~any one of claims 1 to 8~~;
pressing said electrode layer against a surface of a green sheet and adhering said electrode layer to the surface of said green sheet;
stacking the green sheet adhered with said electrode layer to form a green chip; and
firing said green chip.